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Serial No. : 10/044,000
Filed : October 31, 2001
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Attorney's Docket No.: 13292-006001/P2002, 0758 US E



AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 6, line 17 with the following amended paragraph:

Referring to FIG. 8, after singulation of reconstituted wafer water 32, the individual dies 44a-44c can be picked and placed by the die bonder onto an application board, such as a printed circuit board 50, onto which a solder paste is already printed. Printed circuit board 50 has metal contacts 52a-52h, is made of a polymer, and contains copper wire. Solder balls 40a-f of semiconductor chip 16a are soldered to metal contacts 52b-52g. The printed circuit board 50 is then reflowed in a conventional reflow oven, such as the V6 series, manufactured by rehm Anlagenbau GmbH, Germany.

Please replace the paragraph beginning at page 6, line 24 with the following amended paragraph:

The fan-out of metal lines 34a-34c beyond chip edges 36a-36b allows one to shrink the size of chip 16a without requiring a change in dimensions of metal contacts 52a-52h on printed circuit board 50. Standardization is facilitated by holding constant a footprint of chip 44a, i.e. a length L_1 between solder balls 40a-40f 44a-44f.

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